



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-14
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
VN7008AJTR	RRTI*XV43AA5	A	BO2A	2015-10-14
Amount		UoM	Unit type	ST ECOPACK Grade
123.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	3.9x4.9x1.55	16	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	RRTI*XV43AA5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	6.024	mg	supplier	die	Silicon (Si)	7440-21-3		5.667	mg	940737	46073
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.108	mg	17928	878
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1328	65
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.067	mg	11122	545
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.062	mg	10292	504
Die				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	498	24
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1328	65
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.039	mg	6474	317
Die				supplier	glass coating	Glass: Silicon Dioxide (SiO2)	7631-86-9		0.062	mg	10292	504
Leadframe	Copper & its alloys	70.211	mg	supplier	alloy	Copper (Cu)	7440-50-8		69.390	mg	988307	564146
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.069	mg	983	561
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.021	mg	299	171
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.731	mg	10411	5943
Die attach		4.568	mg	JIG - R	Soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.363	mg	955123	35472
Die attach				supplier	Soft Solder	Silver (Ag)	7440-22-4		0.114	mg	24956	927
Die attach				supplier	Soft Solder	Tin (Sn)	7440-31-5		0.091	mg	19921	740
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.723	mg	1000000	5878
encapsulation		39.788	mg	supplier	mold compound	Epoxy Resin	85954-11-6		3.183	mg	79999	25878
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		1.591	mg	39987	12935
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		34.656	mg	871016	281756
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.199	mg	5002	1618
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.159	mg	3996	1293
connections coating	Solder	1.684	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.684	mg	1000000	13691